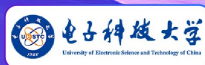


# 第21届IEEE纳米/微米工程与分子系统国际会议

## 2026 IEEE 21<sup>st</sup> International Conference on Nano/Micro Engineered and Molecular Systems

2026年4月17-21日 中国·成都

主办单位



## Sponsors & Exhibition

IEEE-NEMS is a premier conference series sponsored by the IEEE Nanotechnology Council focusing on the promotion of advanced research areas related to M/NEMS, nanotechnology, and molecular technology.

Prior conferences were held in Zhuhai (2025), Kyoto (2024), Jeju (2023), Virtually (2022), Xiamen (2021), Virtually (2020), Bangkok (2019), Singapore (2018), Los Angeles (2017), Matsushima Bay (2016), Xi'an (2015), Hawaii (2014), Suzhou (2013), Kyoto (2012), Kaohsiung (2011), Xiamen (2010), Shenzhen (2009), Hainan Island (2008), Bangkok (2007), and Zhuhai (2006).

2026 IEEE 21st International Conference on Nano/Micro Engineered and Molecular Systems will be held on **April 17-21, 2026 in Chengdu**, China.

### ◆ Organizing Committee

#### Honorary Chair:

Sheng Liu (WHU), Jun Hu (UESTC)

#### General Chair:

Xiaosheng Zhang (UESTC)

#### General Co-Chairs:

Yuan Lin (UESTC), Zenghui Wang (UESTC), Juergen Brugger (EPFL)

### ◆ Conference Topics (including but not limited)

- Micro/Nano Electro-Mechanical Systems (M/NEMS)
- Micro/Nano/Molecular Fabrication
- Micro/Nano Robotics
- Micro/Nano/Molecular Physical/Chemical Sensors/Actuators
- Nano Photonics and Micro/Molecular Optical Devices
- Micro/Nano-Composite Materials and Structures
- Micro/Nano-Bio-/Medical Devices and Systems
- Functional Nanomaterials and Synthesis
- Micro/Nano Integrated Devices/Circuits/Systems
- 3D Printing and Bioprinting
- Micro/Nanofluidics

Sponsorship Package	Platinum	Gold	Silver	Bronze
Complimentary registration	6	4	2	2
Logo on conference website/materials	✓	✓	✓	✓
1 page AD included in the conference program	✓	✓	✓	✓
Brochure/Flyer inserted into the conference bag	Brochure	Flyer	/	/
Logo on screen saver in session rooms	✓	✓	✓	✓
Logo on vertical banner in the conference venue	✓	✓	✓	✓
Exhibit Booth <small>* Refer to the Exhibitor Package for exhibit booth information</small>	2	2	1	/
Participants list (name, affiliation, email) <small>* only participants who agree to share the information with sponsors</small>	✓	✓	/	/
One invited talk in related session (limited)	✓	/	/	/
2-min PR movie prior to one plenary speech	✓	/	/	/
1-min PR movie prior to one technical session	/	✓	/	/
	¥ 80000	¥ 50000	¥ 30000	¥ 20000

## Add-on Opportunities for Sponsors

Conference Bag with logo on bag <small>* 2 Opportunities Available</small>	¥ 15000
Lanyard Sponsor <small>* 1 Opportunities Available (exclusive sponsorship)</small>	¥ 15000
Coffee Break Sponsor <small>* 5 Opportunities Available</small>	¥ 10000

## Exhibitor Package

¥ 15000

Complimentary registration

1

### STANDARD SHELL SCHEME BOOTH

including:

- Exhibition area (9m<sup>2</sup>): 3m wide, 3m depth, 2.5m height
- Non-Lockable Reception Counter (0.76mH)\*1
- Folding Chair\*2
- 220V Power Socket\*1
- Fascia with company name

1

All interior fitting must be contained within the shell scheme unit structure and cannot exceed 2.5m in height.

All signs cannot exceed 2.5m in height.

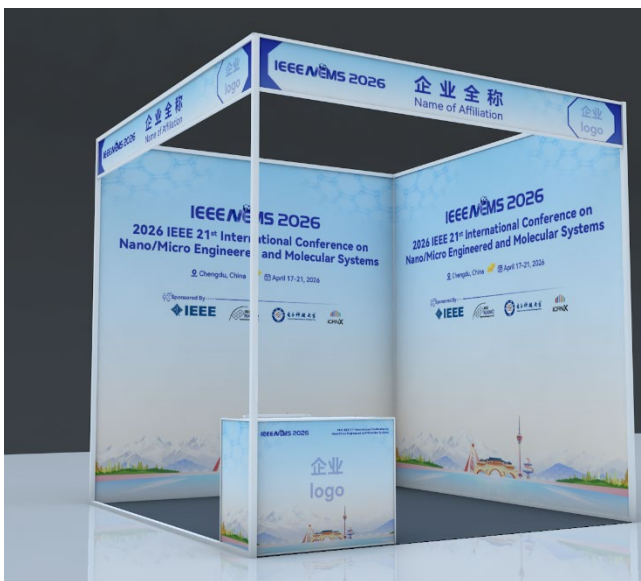
Listed as exhibitor on website and printed materials



Identified as an exhibitor on signs during the Conference



## Booth Size Reference:



## Contact us:

IEEE NEMS 2026

Sponsors & Exhibition Support:

[ieee-nems2026@youngac.cn](mailto:ieee-nems2026@youngac.cn)

&

**Sophie Guan**

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+86-135 5023 0907

\* The schematic diagram shows a double-sided booth. The specific booth type (single-sided or double-sided) shall be subject to final confirmation based on the overall on-site booth layout.

# FLOOR PLAN

## Conference Venue

### Chengdu Airport International Conference Center

Address: No. 1555, South Section of Chengshuang Avenue, Shuangliu District, Chengdu, Sichuan, China



**Booth for Sponsors**

**Booth for Exhibitors**

**Opening & Plenary**

**Parallel Session Rooms**

**Coffee Break Area**

**Poster Area**

Remarks: The floor plan might have minor changes, please subject to the final version in the exhibition manual